




<b>PCN Number:</b>	20210624000.1		<b>PCN Date:</b>	June 25, 2021				
<b>Title:</b>	Qualification of CDAT as an additional Assembly site for Select Devices							
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Dept:</b>	Quality Services					
<b>Proposed 1<sup>st</sup> Ship Date:</b>	Sept 25, 2020	<b>Estimated Sample Availability:</b>	Date provided at sample request					
<b>Change Type:</b>								
<input checked="" type="checkbox"/> Assembly Site	<input type="checkbox"/> Design	<input type="checkbox"/> Wafer Bump Site						
<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Data Sheet	<input type="checkbox"/> Wafer Bump Material						
<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input type="checkbox"/> Wafer Bump Process						
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input type="checkbox"/> Wafer Fab Site						
<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input type="checkbox"/> Wafer Fab Materials						
		<input type="checkbox"/> Wafer Fab Process						
<b>PCN Details</b>								
<b>Description of Change:</b>								
Texas Instruments is pleased to announce the qualification of CDAT as an additional assembly site for the list of devices below. Current assembly site and Material differences are as follows:								
	<b>Clark</b>	<b>CDAT</b>						
Mold Compound	4208625 or 4222198	4222198						
<b>Reason for Change:</b>								
Continuity of Supply								
<b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):</b>								
None								
<b>Anticipated impact on Material Declaration</b>								
<input type="checkbox"/> No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained at the site link below <a href="http://www.ti.com/quality/docs/materialcontentsearch.tsp">http://www.ti.com/quality/docs/materialcontentsearch.tsp</a>						
<b>Changes to product identification resulting from this PCN:</b>								
<b>Assembly Site</b>	<b>Assembly Site Origin (22L)</b>	<b>Assembly Country Code (23L)</b>	<b>Assembly City</b>					
Clark	QAB	PHL	Angeles City, Pampanga					
<b>CDAT</b>	<b>CDA</b>	<b>CHN</b>	<b>Chengdu</b>					
Sample product shipping label (not actual product label)								
   <div style="display: flex; justify-content: space-between;"> <div style="width: 30%;"> <p>MADE IN: Malaysia 2DC: 20:</p> <table border="1"> <tr> <td>MSL '2 /260C/1 YEAR</td> <td>SEAL DT</td> </tr> <tr> <td>MSL 1 /235C/UNLIM</td> <td>03/29/04</td> </tr> </table> <p>OPT: ITEM: 39 <b>LBL: 5A (L)T0:1750</b></p> </div> <div style="width: 60%;"> <p>(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO:USA (22L) ASO: MLA (23L) ACO: MYS</p> </div> </div>					MSL '2 /260C/1 YEAR	SEAL DT	MSL 1 /235C/UNLIM	03/29/04
MSL '2 /260C/1 YEAR	SEAL DT							
MSL 1 /235C/UNLIM	03/29/04							

Product Affected:			
TPS650842A0RSKR	TPS6508640RSKR	TPS6508700RSKT	TPS650944A0RSKR
TPS650842A0RSKT	TPS6508640RSKT	TPS650940A0RSKR	TPS650944A0RSKT
TPS650860A0RSKR	TPS6508641RSKR	TPS650940A0RSKT	TPS650944RSKR
TPS650860A0RSKT	TPS6508641RSKT	TPS650941A0RSKR	TPS650945A0RSKR
TPS65086100RSKR	TPS65086470RSKR	TPS650941A0RSKT	TPS650945A0RSKT
TPS65086100RSKT	TPS65086470RSKT	TPS650942A0RSKR	TPS650947A0RSKR
TPS65086401RSKR	TPS6508700RSKR	TPS650942A0RSKT	TPS650947A0RSKT
TPS65086401RSKT			



TI Information  
Selective Disclosure

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TPA650944RSK	Qual Device: TPA650944RSKR	QBS Product Reference: TPS650842A0RSK	QBS Process Reference: TPS51225C	QBS Package Reference: HD3SS215IRTQR
AC	Autoclave 121C	96 Hours	-	-	-	3/231/0	3/231/0
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	Pass	1/30/0	1/30/0	-
ELFR	Early Life Failure Rate, 125C	48 Hours	-	-	-	-	-
HAST	Biased HAST, 130C/85%RH	96 Hours	2/77/0	-	-	3/231/0	-
HBM	ESD - HBM	2500 V	-	-	1/3/0	2/6/0	-
CDM	ESD - CDM	1500 V	-	-	1/3/0	2/6/0	-
CDM	ESD - CDM	1000 V	1/3/0	-	-	-	-
HTOL	Life Test, 125C	1000 Hours	-	-	1/77/0	3/231/0	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	-	-	-	3/231/0
HTSL	High Temp. Storage Bake, 150C	1000 Hours	-	-	-	3/231/0	-
LU	Latch-up (per JESD78)	-	-	-	2/12/0	2/12/0	-
PD	Physical Dimensions	-	-	-	-	-	3/90/0
SD	Solderability	8 Hours Steam Age	-	-	-	-	3/66/0
TC	Temperature Cycle, - 65/150C	500 Cycles	1/77/0	-	1/77/0	3/231/0	3/231/0

- QBS: Qual By Similarity  
- Qual Device TPS650944RSK is qualified at LEVEL3-260C  
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable  
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours  
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours  
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles  
Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>  
**Green/Pb-free Status:**  
Qualified Pb-Free(SMT) and Green

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